

AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph beginning at page 2, line 21 with the following rewritten version:

Further, in recent years, when the device ~~is~~ is applied for drying a plurality of semiconductor wafers, the semiconductor wafer is enlarged in size, and an interval ~~of~~ between semiconductor wafers is decreased for increasing a the number of semiconductor wafers which are processed simultaneously, ~~in recent years~~. Under such conditions, a disadvantage arises in that ~~intruding~~ introducing of the drying vapor between semiconductor wafers becomes difficult so as to generate a drying mark on the semiconductor wafers.